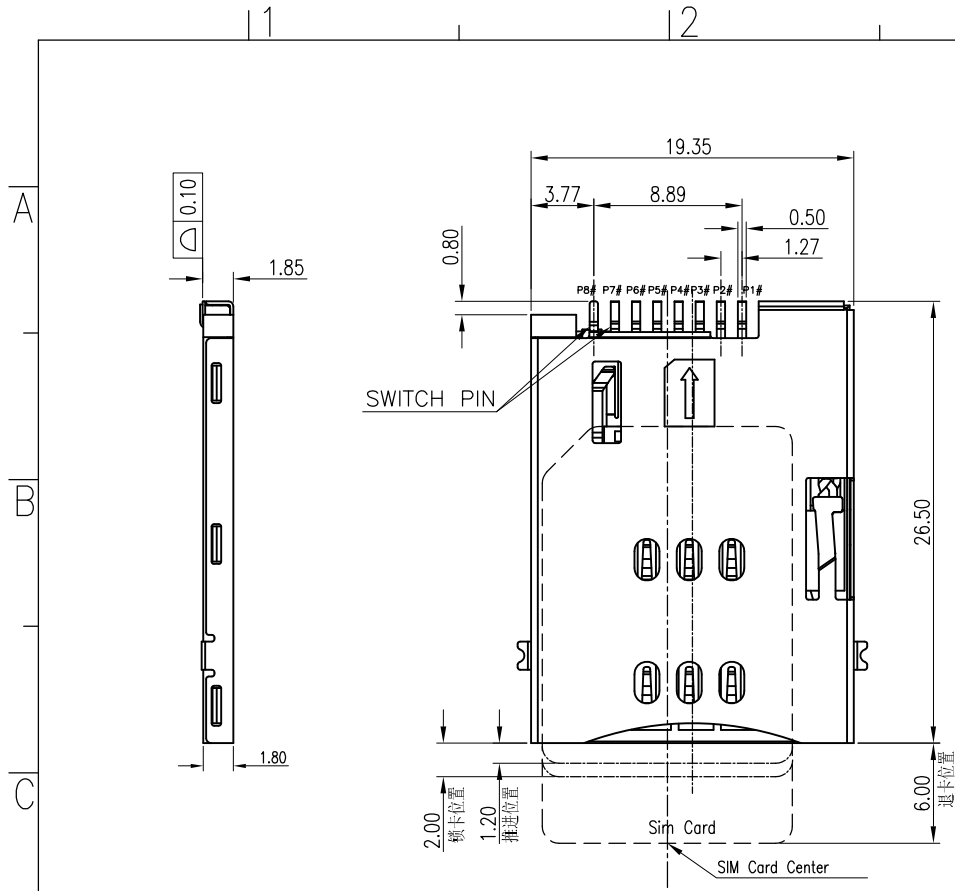




PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL
P8#	DET

C5 GND

C1 VCC

C6 VPP

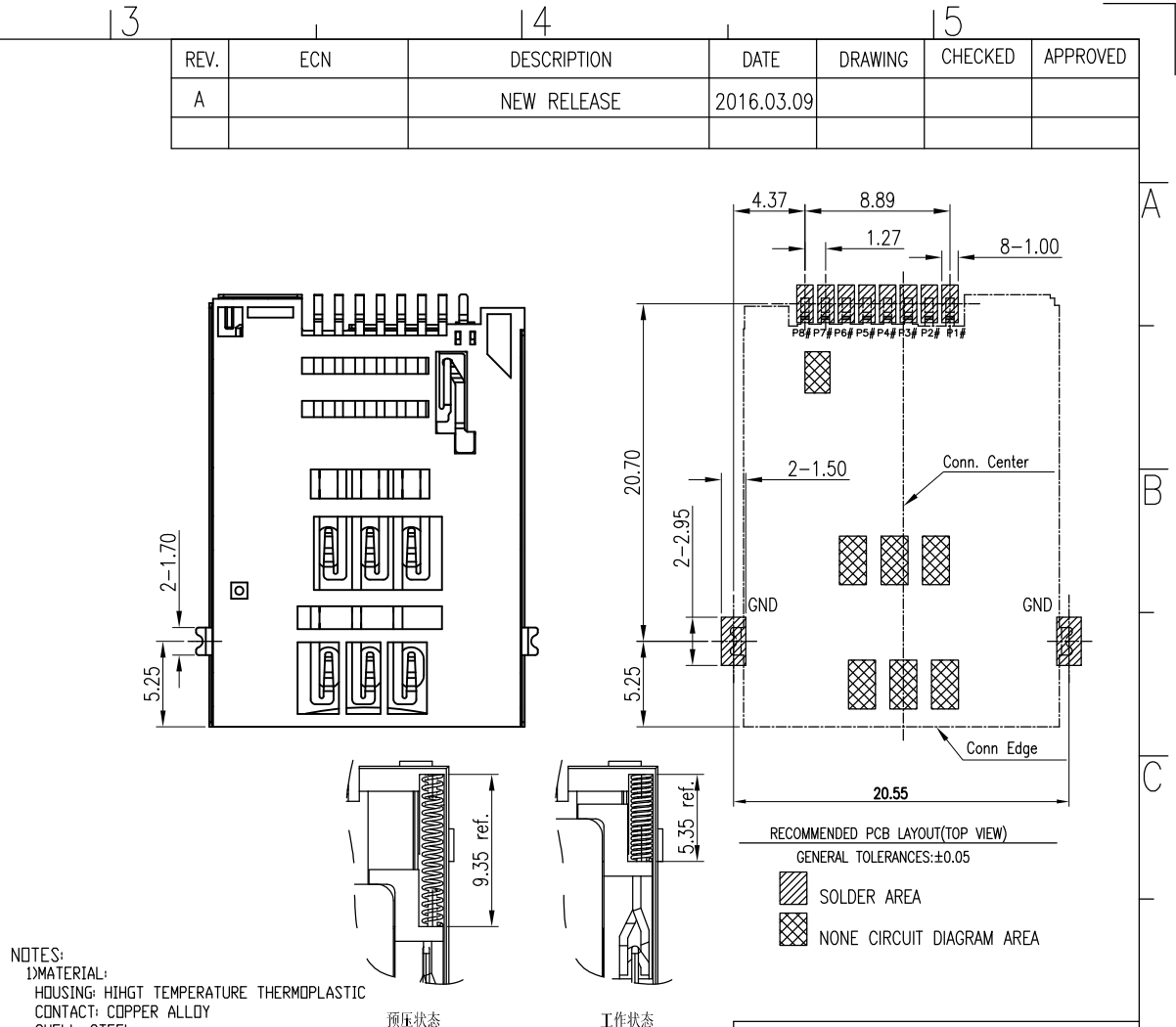
C2 RST

C7 I/O

C3 CLK

SIM 示意图

芯片面朝下视图



NOTES:		1)MATERIAL:	
		HOUSING: HIGH TEMPERATURE THERMOPLASTIC	
		CONTACT: COPPER ALLOY	
		SHELL: STEEL	
		2)FINISH:	
		CONTACT: GOLD FLASH PLATED ON CONTACT AREA;	
		MATT-TIN PLATED ON SOLDER TAILS: WITH	
		ENTIRE CONTACT UNDERPLATED NICKEL.	
		SHELL: GOLD FLASH PLATED ON SOLDER TAILS	
		3.INFRARED REFLOW SOLDERING: 10sec. Min. at 260±10	

MILLIMETERS	INCH	UNITS	MM
X° ± 2°	X° ± 2°	MAT'L	
.X ± 0.30	.XX ± 0.012	SEE NOTES	
.XX ± 0.20	.XXX ± 0.008	FINISH	
.XXX ± 0.10	.XXXX ± 0.004	SEE NOTES	
		QTY	
		SEE NOTES	

XB

东莞市溪榜电子有限公司

DONG GUAN XI BANG ELECTRONICS CO., LTD.

PART NUMBER:

XB-102011322

APPD: Sean

CHKD:

DR: Yang

TITLE:

SIM card 6+2 pin push H1.8

(无定位柱)

DWG NO.:

A-102011322

SCALE

1:1

SHEET

1

REV.

A